INTEGRATED CIRCUITS

DATA SHEET



74ABT16260/74ABTH16260

12-bit to 24-bit multiplexed D-type latches (3-State)

Product specification Supersedes data of 1996 Nov 20 IC23 Data Handbook





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FEATURES

- ESD protection exceeds 2000V per Mil-Std-883C, Method 3015; exceeds 200V using machine model (C = 200pF, R = 0).
- Latch-up performance exceeds 500mA per JEDEC Standard JESD-17.
- Distributed V_{CC} and GND pin configuration minimizes high-speed switching noise.
- Flow-through architecture optimizes PCB layout.
- High-drive outputs (–32mA I_{OH}, 64mA I_{OL}).
- 74ABTH16260 incorporates bus-hold inputs which eliminate the need for external pull-up resistors.
- Package options:
 - 56-pin plastic Shrink Small-Outline Package (SSOP)
 - 56-pin plastic Thin Shrink Small-Outline Package (TSSOP)

DESCRIPTION

The 74ABT16260/74ABTH16260 is a 12-bit to 24-bit multiplexed D-type latch used in applications where two separate data paths must be multiplexed onto, or demultiplexed from, a single data path. Typical applications include multiplexing and/or demultiplexing of address and data information in microprocessor or bus-interface applications. This device is alto useful in memory-interleaving applications.

Three 12-bit I/O ports (A1–A12, 1B1–1B12, and 2B1–2B12) are available for address and/or data transfer. The output enable ($\overline{OE1B}$, $\overline{OE2B}$, and \overline{OEA}) inputs control the bus transceiver functions. The $\overline{OE1B}$ and $\overline{OE2B}$ control signals also allow bank control in the A to B direction.

Address and/or data information can be stored using the internal storage latches. The latch enable (LE1B, LE2B, LEA1B, and LEA2B) inputs are used to control data storage. When the latch enable input is high, the latch is transparent. When the latch enable input goes low, the data present at the inputs is latched and remains latched until the latch enable input is returned high.

To ensure the high-impedance state during power-up or power-down, \overline{OE} should be tied to V_{CC} through a pull-up resistor; the minimum value of the resistor is determined by the current sinking capability of the driver.

The 74ABTH incorporates the bus hold feature. The 74ABT does not include bus hold feature. Both parts are available in 56-pin SSOP and TSSOP.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS T _{amb} = 25°C; GND = 0V	TYPICAL	UNIT
t _{PLH}	Propagation delay	C: -50 pE	2.8	no
t _{PHL}	nAx to nBx nBx to nAx	C _L = 50 pF	2.5	ns
C _{IN}	Input capacitance	$V_I = 0 \text{ V or } V_{CC}$	4	pF
C _{OUT}	Output capacitance	$V_{I/O} = 0 \text{ V or } 5.0 \text{ V}$	6	pF
I _{CCZ}	Total supply current	Outputs disabled	100	μΑ

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
56-Pin Plastic SSOP Type III	-40°C to +85°C	74ABT16260 DL	BT16260 DL	SOT371-1
56-Pin Plastic TSSOP Type II	-40°C to +85°C	74ABT16260 DGG	BT16260 DGG	SOT364-1
56-Pin Plastic SSOP Type III	-40°C to +85°C	74ABTH16260 DL	BH16260 DL	SOT371-1
56-Pin Plastic TSSOP Type II	-40°C to +85°C	74ABTH16260 DGG	BH16260 DGG	SOT364-1

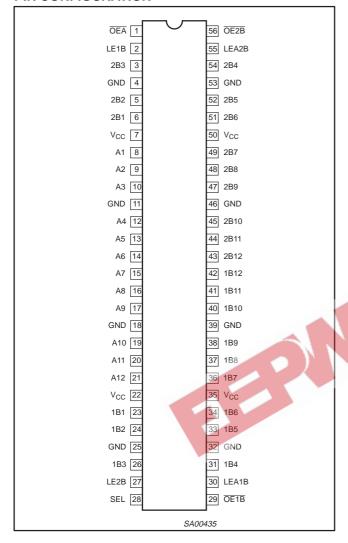
PIN DESCRIPTION

PIN NUMBER	SYMBOL	FUNCTION		
8, 9, 10, 12, 13, 14, 15, 16, 17, 19, 20, 21	An	Data inputs/outputs (A)		
23, 24, 26, 31, 33, 34, 36, 37, 38, 40, 41, 42	1Bn	Data inputs/outputs (B1)		
6, 5, 3, 54, 52, 51, 49, 48, 47, 45, 44, 43	2Bn	Data inputs/outputs (B2)		
1, 29, 56	OEA, OE1B, OE2B	Output enable input (active low)		
2, 27, 30, 55	LE1B, LE2B, LEA1B, LEA2B	Latch enable inputs		

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PIN CONFIGURATION



FUNCTION TABLES

B to A ($\overline{OEB} = H$)

		INP	UTS			OUTPUT
1B	2B	OEA	Α			
Н	Х	Н	Н	Х	L	Н
L	Х	Н	Н	Х	L	L
X	Х	Н	L	Х	L	A0
X	Н	L	Х	Н	L	Н
X	L	L	Х	Н	L	L
X	Х	L	Х	L	L	A0
Х	Х	Х	Х	Х	Н	Z

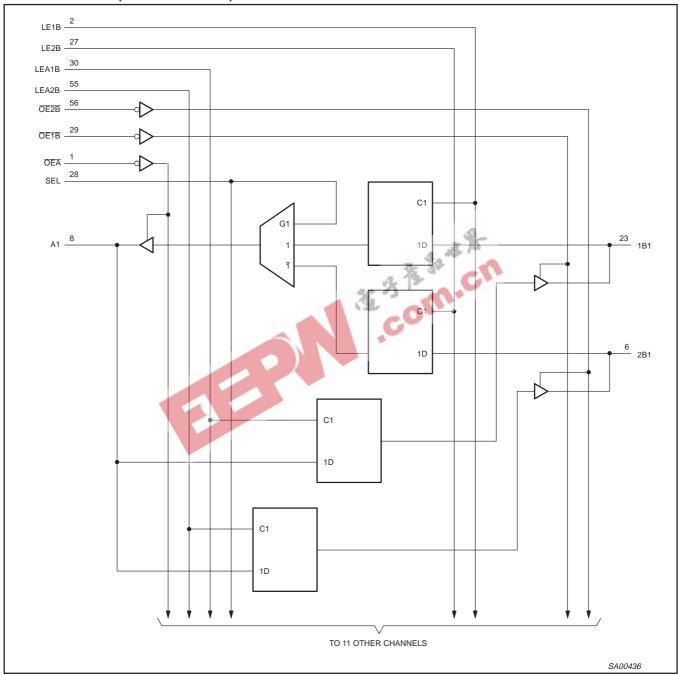
A to B ($\overline{OEA} = H$)

		INPUTS			OUT	PUT
Α	LEA1B	LEA2B	LEA2B OE1B OE2B		1B	2B
Н	_ HI_	H	L	L	Н	Н
La	Н	H.	L	L	L	L
KH2	H	T	L	L	Н	2B0
L	Ob.	L	L	L	L	2B0
H	L	Н	L	L	1B0	Н
L	L	Н	L	L	1B0	L
X	L	L	L	L	1B0	2B0
X	Х	Х	Н	Н	Z	z
X	Х	Х	L	Н	Active	z
X	Х	Х	Н	L	Z	Active
Х	Х	Х	L	L	Active	Active

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LOGIC DIAGRAM (POSITIVE LOGIC)



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ABSOLUTE MAXIMUM RATINGS

Over operating free-air temperature range (unless otherwise specified)¹

SYMBOL	PARAMETER	CONDITIONS	LIM	UNIT	
STIMIBUL	PARAMETER	CONDITIONS	MIN	MAX	UNII
V _{CC}	Supply voltage range		-0.5	7	V
VI	Input voltage range	see Note 2	-0.5	7	V
V _O	Voltage range applied to any output in the high state or power-off state		-0.5	5.5	V
Io	Current into any output in the low state			128	mA
I _{IK}	Input clamp current	V _I < 0		-18	mA
I _{OK}	Output clamp current	V _O < 0		-50	mA
	Maximum power dissipation at T _{amb} = 55°C (in still air)	see Note 3		1.4	W
T _{stg}	Storage temperature range		-65	+150	°C

NOTES:

- Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "Recommended Operating Conditions" is not implied. Exposure to absolute maximum rated conditions for extended periods may affect device reliability.

 2. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

 3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

RECOMMENDED OPERATING CONDITIONS¹

CVMDOL	PARAMETER	LIM	UNIT		
SYMBOL	PARAMETER		MIN	MAX	UNII
V _{CC}	Supply voltage		4.5	5.5	V
V _{IH}	High-level input voltage		2		V
V _{IL}	Low-level input voltage			0.8	V
VI	Input voltage		0	V _{CC}	V
l _{OH}	High-level output current			-32	mA
l _{OL}	Low-level output current			64	mA
ΔtΔ/ν	Input transition rise or fall rate	Outputs enabled		10	ns/V
ΔtΔ/V _{CC}	Power-up ramp rate		200		μs/V
T _{amb}	Operating free-air temperature		-40	+85	°C

NOTE:

^{1.} Unused or floating inputs must be held high or low.

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DC ELECTRICAL CHARACTERISTICS

						LIMITS			
SYMBOL	PARAMETER	TEST CONDITIONS	Tai	_{mb} = +25	°C	T _{amb} =	–40°C 35°C	UNIT	
				Min	Тур	Max	Min	Max	
V _{IK}	Input clamp voltage	$V_{CC} = 4.5V; I_{IK} = -18mA$			-0.8	-1.2		-1.2	V
		$V_{CC} = 4.5V; I_{OH} = -3mA; V_{I} = V$	2.5	2.9		2.5		V	
V _{OH}	High-level output voltage	$V_{CC} = 5.0V; I_{OH} = -3mA; V_{I} = V$	3.0	3.4		3.0		V	
		$V_{CC} = 4.5V; I_{OH} = -32mA; V_{I} = -32mA$	2.0	2.4		2.0		V	
V _{OL}	Low-level output voltage	$V_{CC} = 4.5V; I_{OL} = 64mA; V_{I} = V$		0.42	0.55		0.55	V	
II	Input leakage current	$V_{CC} = 5.5V$; $V_I = V_{CC}$ or GND	Control pins		±0.01	±1		±1	μА
		$V_{CC} = 5.5V$; $V_I = V_{CC}$ or GND	Data pins			±3		±5	μΑ
		$V_{CC} = 4.5V; V_I = 0.8V$	A or B	75			75		
I _{HOLD}	Bus Hold current	$V_{CC} = 4.5V; V_{I} = 2.0V$	ports	-75			-75		μΑ
		$V_{CC} = 5.5V$; $V_I = 0$ to 5.5V	4	±500			±500		
I _{OFF}	Power-off leakage current	$V_{CC} = 0.0V$; V_O or $V_I \le 4.5V$. %	-	±5.0	±100		±100	μΑ
I _{PU} /I _{PD}	Power-up/down 3-State output current	V_{CC} = 2.0V; V_O = 0.5V; V_I = GND or V_{CC} ; V_{OE} = V_{CC}	63	40.0	±60	±200		±200	μА
I _{OZH}	3-State output High current	$V_{CC} = 5.5V; V_{O} = 2.7V; V_{I} = V_{IL}$	or V _{IH}		1.0	10		10	μΑ
I _{OZL}	3-State output Low current	$V_{CC} = 5.5 \text{ V}; V_{O} = 0.5 \text{ V}; V_{I} = V_{IL}$	or V _{IH}		-1.0	-10		-10	μΑ
I _{CEX}	Output high leakage current	$V_{CC} = 5.5V; V_{O} = 5.5V; V_{I} = GN$	ID or V _{CC}			50		50	μΑ
Io	Output current ¹	$V_{CC} = 5.5V; V_O = 2.5V$		-50	-100	-225	-50	-225	mA
		$V_{CC} = 5.5V$; Outputs High, $V_{I} =$	GND or V _{CC}		0.2	1.5		1.5	
I _{CC}	Quiescent supply current	$V_{CC} = 5.5V$; Outputs Low, $V_I = 0$	GND or V _{CC}		8	19		19	mA
-00		$V_{CC} = 5.5V$; Outputs 3-State; $V_{I} = GND$ or V_{CC}		0.1	1.0		1.0		
Δl _{CC}	Additional supply current per input pin ²	Outputs enabled, one input at 3 inputs at V_{CC} or GND; $V_{CC} = 5$.	.4V, other 5V		0.1	1.5		1.5	mA

- Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
 This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.
 This is the bus hold minimum overdrive current required to force the input to the opposite logic state.

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AC ELECTRICAL CHARACTERISTICS

Over recommended operating free-air temperature range (unless otherwise noted)

SYMBOL	PARAI	METER	V _{CC}	= 5V, T _{amb} = 3	25°C	T _{amb} = -40	°C to +85°C	UNIT
STWIBUL	FROM (INPUT)	TO (OUTPUT)	MIN	TYP	MAX	MIN	MAX	UNII
t _{PLH}	A or B	B or A	1	2.8	4.8	1	5.6	ns
t _{PHL}	AOIB	BOLA	1	2.5	5	1	5.9	ns
t _{PLH}	ΙĒ	A or B	1.1	3.2	4.9	1.1	5.8	ns
t _{PHL}	LE	AUIB	1.1	3.2	4.9	1.1	5.3	ns
	SEL (B1)	А	1.3	3.2	4.6	1.3	5.3	ns
t _{PLH}	SEL (B2)	А	1.1	2.8	4.9	1.1	6	ns
	SEL (B1)	А	1.5	3.0	4.4	1.5	4.4	ns
t _{PHL}	SEL (B2)	А	1.6	2.6	5.1	1.6	5.9	ns
t _{PZH}	ŌĒ	A or B	1	2.9	4.7	1	5.7	ns
t _{PZL}	OE	AUIB	1.6	2.2	5.1	1.6	5.8	ns
t _{PHZ}	ŌĒ	A or B	2.2	4.1	5.4	2.2	6.4	ns
t _{PLZ}	OE .	AOLP	1.3	3.2	4.4	1.3	4.8	ns

t_{PLZ}	OL.	A OI B	1.3	3.2	4.4	1.3	4.8	ns			
	AC SETUP CHARACTERISTICS Over recommended operating free-air temperature range (unless otherwise noted)										
SYMBOL	,	PARAMETER		V _{CC} = 5V, T	_{amb} = 25°C	T _{amb} = -40°	UNIT				
STIMBUL		ARAWETER		MIN	MAX	MIN	MAX	UNII			
t _w	Pulse duration, LE1B, LE	2B, LEA1B, or LEA2B hi	gh	3.3		3.3		ns			
t _{su}	Setup time, data before LE1B, LE2B, LEA1B, or LEA2B↓			1.5		1.5		ns			
t _h	Hold time, data after LE1	Hold time, data after LE1B, LE2B, LEA1B, or LEA2B↓				1		ns			

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AC WAVEFORMS

 $V_M = 1.5V$ for all waveforms

The outputs are measured one at a time with one transition per measurement.

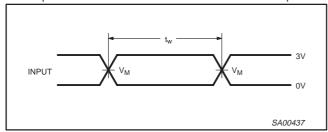


Figure 1. Pulse duration

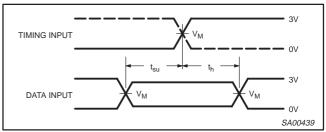
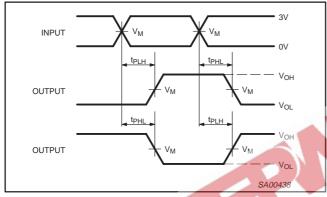
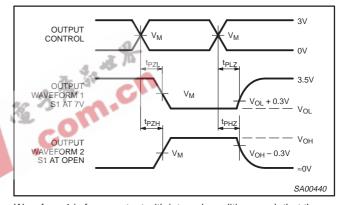


Figure 3. Setup and hold times



All input pulses are supplied by generators having the following characteristics: PRR \leq 10MHz, Z_{O} = 50Ω, t_{Γ} \leq 2.5ns, t_{f} \leq 2.5ns,

Figure 2. Propagation delay times; inverting and non-inverting outputs



Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

Figure 4. Enable and disable times; low- and high-level enabling

TEST LOAD CIRCUIT

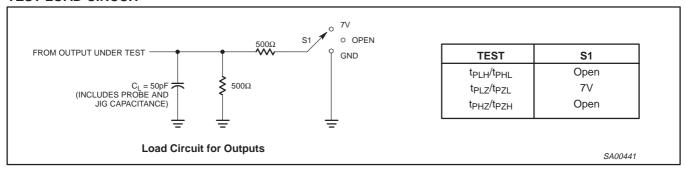


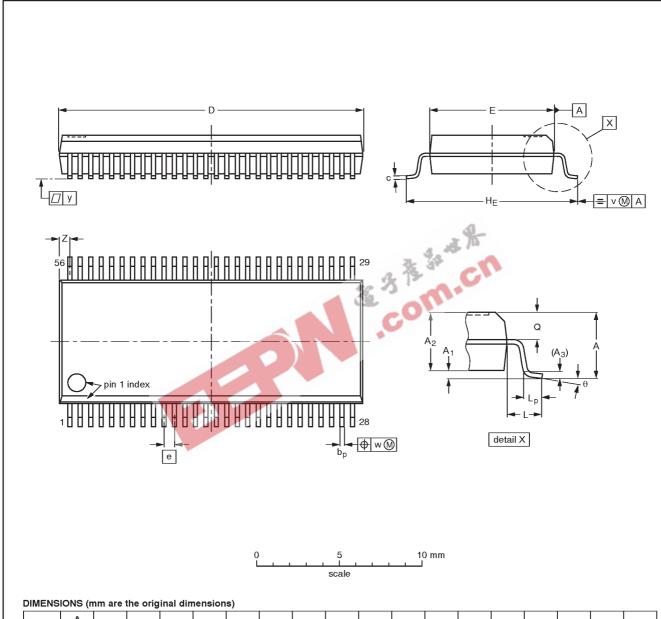
Figure 5. Test load circuit

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SSOP56: plastic shrink small outline package; 56 leads; body width 7.5 mm

SOT371-1



UNIT	A max.	Α ₁	A ₂	A ₃	рb	O	D ⁽¹⁾	E ⁽¹⁾	е	HE	٦	Lp	œ	v	w	у	Z ⁽¹⁾	θ
mm	2.8	0.4 0.2	2.35 2.20	0.25	0.3 0.2	0.22 0.13	18.55 18.30	7.6 7.4	0.635	10.4 10.1	1.4	1.0 0.6	1.2 1.0	0.25	0.18	0.1	0.85 0.40	8° 0°

Note

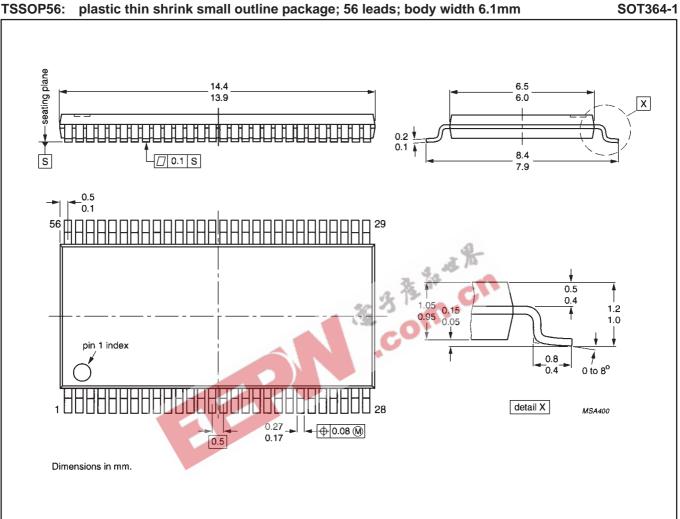
1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT371-1		MO-118AB				-93-11-02 95-02-04

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plastic thin shrink small outline package; 56 leads; body width 6.1mm



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NOTES



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Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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